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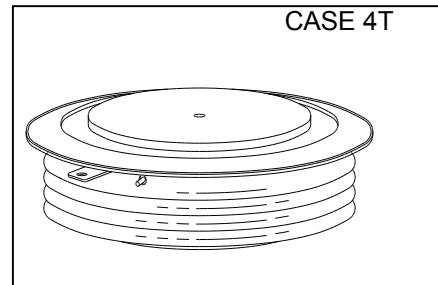
Runau Electronics(Yangzhou)Manufacturing Co.,Ltd 500 - 1400 V_{DRM}; 2575 A rms

HIGH POWER THYRISTOR FOR PHASE CONTROL APPLICATIONS**Features:**

- . All Diffused Structure
- . Interdigitated Amplifying Gate Configuration
- . Blocking capability up to 1400 volts
- . Guaranteed Maximum Turn-Off Time
- . High dV/dt Capability
- . Pressure Assembled Device

ELECTRICAL CHARACTERISTICS AND RATINGS**Blocking - Off State**

Device Type	V _{RRM} (1)	V _{DRM} (1)	V _{RSM} (1)
YC450E	500	500	600
YC450M	600	600	720
YC450N	800	800	960
YC450P	1000	1000	1150
YC450PB	1200	1200	1300
YC450PD	1400	1400	1500

V_{RRM} = Repetitive peak reverse voltageV_{DRM} = Repetitive peak off state voltageV_{RSM} = Non repetitive peak reverse voltage (2)

Notes:

All ratings are specified for T_j=25 °C unless otherwise stated.

(1) All voltage ratings are specified for an applied 50Hz/60Hz sinusoidal waveform over the temperature range -40 to +125 °C.

(2) 10 msec. max. pulse width

(3) Maximum value for T_j = 125 °C.(4) Minimum value for linear and exponential waveshape to 80% rated V_{DRM}. Gate open. T_j = 125 °C.

(5) Non-repetitive value.

(6) The value of di/dt is established in accordance with EIA/NIMA Standard RS-397, Section 5-2-2-6. The value defined would be in addition to that obtained from a snubber circuit, comprising a 0.2 µF capacitor and 20 ohms resistance in parallel with the thristor under test.

Repetitive peak reverse leakage and off state leakage	I _{RRM} / I _{DRM}	15 mA 65 mA (3)
Critical rate of voltage rise	dV/dt (4)	400 V/µsec

Conducting - on state

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Average value of on-state current	I _{T(AV)}		1640		A	Sinewave, 180° conduction, T _c =65°C
RMS value of on-state current	I _{TRMS}		2575		A	Nominal value
Peak one cycle surge (non repetitive) current	I _{TSM}		28500 26000		A A	8.3 msec (60Hz), sinusoidal wave- shape, 180° conduction, T _j = 125 °C 10.0 msec (50Hz), sinusoidal wave- shape, 180° conduction, T _j = 125 °C
I square t	I ² t		3.4x10 ⁶		A ² s	8.3 msec
Latching current	I _L		800		mA	V _D = 24 V; R _L = 12 ohms
Holding current	I _H		400		mA	V _D = 24 V; I = 2.5 A
Peak on-state voltage	V _{TM}		1.4		V	I _{TM} = 3000 A;
Critical rate of rise of on-state current (5, 6)	di/dt		400		A/µs	Switching from V _{DRM} ≤ 1000 V, non-repetitive
Critical rate of rise of on-state current (6)	di/dt		150		A/µs	Switching from V _{DRM} ≤ 1000 V

Gating

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Peak gate power dissipation	P _{GM}		200		W	t _p = 40 us
Average gate power dissipation	P _{G(AV)}		5		W	
Peak gate current	I _{GM}		10		A	
Gate current required to trigger all units	I _{GT}		300 200 125		mA	V _D = 6 V; R _L = 3 ohms; T _j = -40 °C V _D = 6 V; R _L = 3 ohms; T _j = +25 °C V _D = 6 V; R _L = 3 ohms; T _j = +125 °C
Gate voltage required to trigger all units	V _{GT}	0.30	5 3		V	V _D = 6 V; R _L = 3 ohms; T _j = -40 °C V _D = 6 V; R _L = 3 ohms; T _j = 0-125 °C V _D = Rated V _{DRM} ; R _L = 1000 ohms; T _j = + 125 °C
Peak negative voltage	V _{GRM}		5		V	

Dynamic

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Delay time	t _d		1.5	0.7	μs	I _{TM} = 50 A; V _D = 67% V _{DRM} Gate pulse: V _G = 30 V; R _G = 10 ohms; t _r = 0.1 μs; t _b = 20 μs
Turn-off time (with V _R = -5 V)	t _q		250	150	μs	I _{TM} > 1000 A; di/dt = 25 A/μs; V _R ≥ -5 V; Re-applied dV/dt = 20V/μs linear to 67% V _{DRM} ; T _j = 125 °C; Duty cycle ≥ 0.01%
Reverse recovery charge	I _{rr}				μC	I _{TM} > 1000 A; di/dt = 25 A/μs; V _R ≥ -50 V; T _j = 125 °C

THERMAL AND MECHANICAL CHARACTERISTICS AND RATINGS

Parameter	Symbol	Min.	Max.	Typ.	Units	Conditions
Operating temperature	T _j	-40	+125		°C	
Storage temperature	T _{stg}	-40	+150		°C	
Thermal resistance - junction to case	R _{Θ(j-c)}		0.025 0.050		°C/W	Double sided cooled Single sided cooled
Thermal resistance - case to sink	R _{Θ(c-s)}		0.010 0.020		°C/W	Double sided cooled * Single sided cooled
Mounting force	P	5000 24.5	6000 26.4		lb. kN	
Weight	W			16 0.46	oz Kg.	

* Mounting surfaces smooth, flat and greased

